

DERWENT-ACC-NO: 1984-303625

DERWENT-WEEK: 198449

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TITLE: Printed circuit board mfr. - forming etching resist by
offset printing providing reliable resist and high
productivity NoAbstract NoDwg

PATENT-ASSIGNEE: MATSUSHITA ELEC IND CO LTD[MATU]

PRIORITY-DATA: 1983JP-0063277 (April 11, 1983)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 59188991 A	October 26, 1984	N/A	004	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 59188991A	N/A	1983JP-0063277	April 11, 1983

INT-CL (IPC): H05K003/06

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS: PRINT CIRCUIT BOARD MANUFACTURE FORMING ETCH
RESIST OFFSET PRINT
RELIABILITY RESIST HIGH PRODUCE NOABSTRACT

DERWENT-CLASS: G05 L03 V04

CPI-CODES: G02-A05B; G06-D06; L03-H04E3;

DERWENT-ACC-NO: 1984-252691

DERWENT-WEEK: 198441

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TITLE: Printed circuit board - produced by forming etching
resist film on copper foil of copper clad laminate using
offset printing technique NoAbstract NoDwg

PATENT-ASSIGNEE: MATSUSHITA ELEC IND CO LTD[MATU]

PRIORITY-DATA: 1983JP-0023863 (February 17, 1983)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 59151488 A	August 29, 1984	N/A	004	N/A

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 59151488A	N/A	1983JP-0023863	February 17, 1983

INT-CL (IPC): H05K003/06

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS: PRINT CIRCUIT BOARD PRODUCE FORMING ETCH RESIST
FILM COPPER FOIL
COPPER CLAD LAMINATE OFFSET PRINT TECHNIQUE NOABSTRACT

ADDL-INDEXING-TERMS:
PCB

DERWENT-CLASS: L03 V04

CPI-CODES: L03-H04E2;